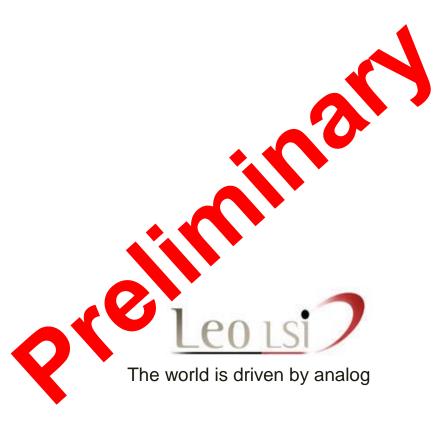
STA1.01A Datasheet 32-Channel CMOS Analog Switch IC

16 March 2016 e-mail: leolsi@leolsi.com



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GENERAL DESCRIPTION

The STA IC is a monolithic CMOS device containing 64 independently selectable switches. These switches are fabricated with an advanced submicron CMOS process that provides low power dissipation, low on resistance, low leakage currents, and high signal bandwidth. The STA IC is designed to operate in 3.3V for digital circuits and 5V for analog switches. Each switch can operate with a wide input and output voltage range. The off-leakage current is only 30nA at room temperature of 25°C.

All digital inputs have 0.8-V to 2.4-V input noise margin to ensure TTL/CMOS-logic compatibility when using a 3.3-V power supply.

FEATURE

3.3V logic-compatible input (V_{IH} =2.4V, V_{IL} =0.8V) Dual supply operation: 3.3V for digital, 5V for analog. Analog signal frequency: DC-to-1MHz Low on-resistance: 0.6 Ω (@typ) Wide range analog input from 0V to 5V Chip-ID programmable with OTP memory Multi-channel switch control Switching control using CMOS IF command 81-pin FBGA package

APPLICATIONS

Data-acquisition systems Mechanical reed-relay replacement Communication systems

FUNCTIONAL DIAGRAM

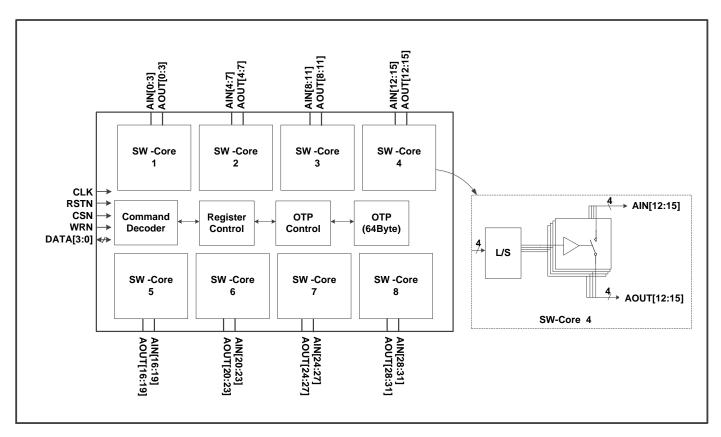


Figure 1. Functional Diagram



LEO LSI 2 DS_STA1.01_V1.4

ABSOLUTE MAXIMUM RATINGS_____

(All Voltages Referenced to GND, Unless Otherwise Noted.)

AVDD (for Analog Switch)	0.3V to +6V
DVDD (for Digital Control)	0.3V to +4.5V
Voltage at any digital pin	0.3V to +4.5V
Voltage at any analog pin	0.3V to +6V
Continuous current into any terminal	200mA
Peak current into analog switch I/O	250mA
(current pulse with 1ms and 10% duty	cycle)

Operating temperature range	40°C to +85°C
Storage temperature range	65°C to +125°C
Junction temperature	+150°C
ESD protection on all pins (HBM, MM	۷)≥2kV, 200V

Notice: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at those or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS_____

AVDD=5.0V, AVSS=0V, DVDD=3.3V, DVSS=0V, and TA = +25°C, unless otherwise noted.

PARAMETER		CVMDOL	CONDITION	VALUE			UNIT
		SYMBOL CONDITION -		MIN	TYP	MAX	UNII
POWER SU	JPPLIES						
Analog Sup	ply Voltage	AVDD		4.5	5	5.5	V
Digital Supp	oly Voltage	DVDD		3.0	3.3	3.6	V
Analog Gro	und Voltage	AVSS		-	0	-	V
Digital Grou	ınd Voltage	DVSS		-	0	-	V
ANALOG S	SWITCH						
Signal	Input Range	V _{AIN}		0		AVDD	V
Range	Output Range	V _{AOUT}		0		AVDD	V
Channel Or	Current	I _{CH_ON}	AVDD=5V, V _{AIN} =0V or 5V			200	mA
Switch On-r	esistance	R _{ON}	V _{AIN} =0V to AVDD , I _{CH_ON} =-1mA		0.6	1	Ω
	Source Off Leakage Current	I _{S_OFF}	AVDD=5V, V _{AIN} =5, V _{AOUT} =0V		0.1	1	uA
Leakage Current	Drain Off Leakage Current	I _{D_OFF}	AVDD=5V, V _{AIN} =0V, V _{AOUT} =5V		0.1	1	uA
	Channel On Leakage Current	I _{CH_OFF}	AVDD=5V, V _{AIN} =0V or 5V		0.1	1	uA



LEO LSI 3 DS_STA1.01_V1.4

ELECTRICAL CHARACTERISTICS (Continued)

AVDD=5.0V, AVSS=0V, DVDD=3.3V, DVSS=0V, and TA = +25°C, unless otherwise noted.

DADA	METED	SYMBOL	CONDITION	VALUE			UNIT	
PARAMETER		STMBOL CONDITION		MIN	TYP	MAX		
DIGITAL I/O								
Logic Input	Input High	V _{IH}		0.7* DVDD			V	
Voltage	Input Low	V _{IL}				0.3* DVDD	V	
Logic Input	Input High	I _{IH}		-1		1	uA	
Current	Input Low	I _{IL}		-1		1	uA	
SWITCH DYNA	AMIC CHARACTE	RISTICS						
Switching Time	Turn ON Time	t _{ON}	Clock base (calculate for special condition)		175		ns	
	Turn OFF Time	toff			235		ns	
	Input Off- Capacitance	C _{AIN_OFF}			300		pF	
Capacitance	Output Off- Capacitance	C _{AOUT_OFF}			300		pF	
	Output On- Capacitance	C _{AOUT_ON}			600		pF	
Off-Isolation			No Load, f _{SW} =1MHz	-16			dB	
Channel-to-Cha	annel Crosstalk		No Load, f _{SW} =1MHz	-41			dB	
POWER CONSUMPTION								
Analog	Static	I _{AVDD_ST}	AVDD=5V			1	uA	
Operating Current (AVDD)	Dynamic	I _{AVDD_DYN}	AVDD=5V, f _{SW} =1.25MHz (Note1), All switch On/Off operating simultaneously			50	mA	
Digital	Static	I _{DVDD_ST}	DVDD=3.3V			1	uA	
Digital Operating Current (DVDD)	Dynamic	I _{DVDD_DYN}	DVDD=3.3V, f _{CLK} =10MHz (Note1), Combined operation of Reset, Group-On and DUT-Reject			400	uA	

 $oldsymbol{Note1}$: The f_{CLK} is the frequency of digital signal CLK.

When the f_{CLK} is 10MHz, the maximum switching frequency (f_{SW}) is 1.25MHZ (1-clock command).



TIMING CHARACTERISTICS_____

AVDD=5.0V, AVSS=0V, DVDD=3.3V, DVSS=0V, and TA = +25°C, unless otherwise noted.

PARAMETER	SYMBOL	CONDITION	VALUE			UNIT			
TANAMETER	OTMBOL	GONDITION	MIN	TYP	MAX	O.u.			
DIGITAL I/O SIGNALS	DIGITAL I/O SIGNALS								
CLK Period	t _{PERIOD}				20	ns			
DATA to CLK Setup Time	t _{DS}		10			ns			
DATA to CLK Hold Time	t _{DH}		5			ns			
CSN to CLK Setup Time	tcs		10			ns			
CSN to CLK Hold Time	tсн		5			ns			
WRN to CLK Setup Time	t _{WS}		10			ns			
WRN to CLK Hold Time	t _{WH}		5			ns			
POWER AND RESET SEQUENC	E								
Power-up Period	t _{PU}		500			us			
Power-down Period	t _{PD}		500			us			
Power-on Reset Time	t _{RST}		2			us			
Chip-ID Read Routine Time	t _{IDRD}		2			us			
SWITCH ON/OFF TIMING DIAGRAM									
Switch Control Enable Time	t _{SWEN}		1			us			
1-Clock Command Control Time	t _{SW1}				3	cycle			
2-Clock Command Control Time	t SW2				6	cycle			



LEO LSI 5 DS_STA1.01_V1.4

Timing Diagram of Digital I/O Signals

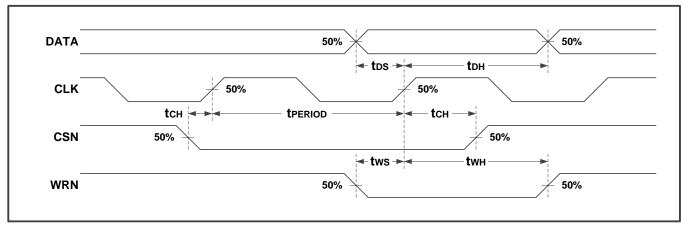


Figure 2. Timing Diagram of Digital Signals

Power and Reset sequence

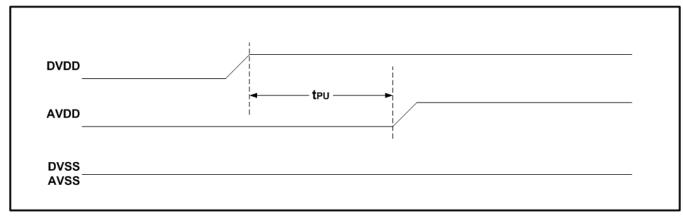


Figure 3. Power-up Sequence

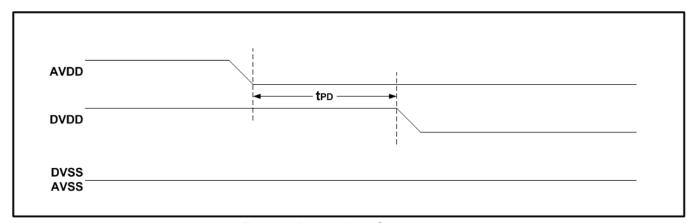


Figure 4. Power-down Sequence



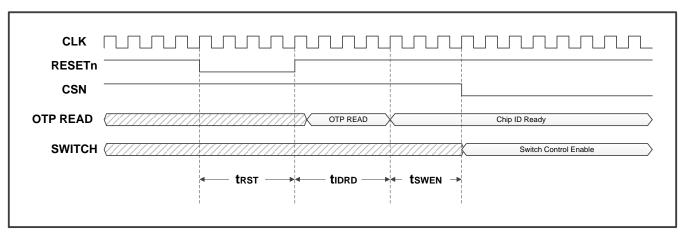


Figure 5. Reset and Stand-by Sequence

Switch On/Off Timing Diagram

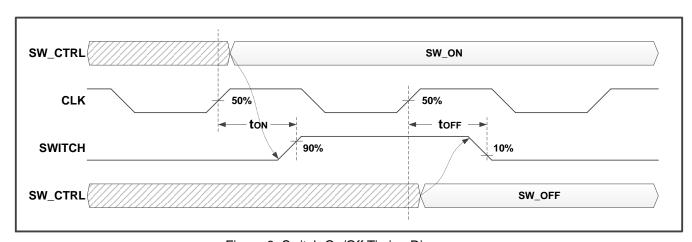


Figure 6. Switch On/Off Timing Diagram



PIN MAPPING TABLE_____

	1	2	3	4	5	6	7	8	9	
Α	TEST_IN	AOUT[31]	AIN[31]	WRN	CSN	RSTN	VPP	AOUT[24]	AIN[24]	A
В	PAGE_UP	AIN[0]	AOUT[30]	AIN[30]	AIN[29]	AOUT[26]	AIN[26]	AIN[25]	AOUT[23]	В
С	DVSS	AOUT[0]	AIN[1]	AOUT[29]	AOUT[28]	AIN[27]	AOUT[25]	AOUT[22]	AIN[23]	С
D	DVDD	AOUT[3]	AOUT[1]	AIN[2]	AIN[28]	AOUT[27]	AOUT[21]	AIN[22]	AIN[20]	D
E	CLK	AIN[4]	AIN[3]	AOUT[2]	AVSS	AVDD	AIN[21]	AOUT[20]	AOUT[19]	E
F	DATA[0]	AOUT[4]	AIN[5]	AOUT[5]	AVDD	AVSS	AIN[18]	AOUT[18]	AIN[19]	F
G	DATA[1]	AIN[7]	AIN[6]	AOUT[6]	AOUT[11]	AIN[12]	AOUT[17]	AIN[17]	AOUT[16]	G
н	DATA[2]	AOUT[7]	AIN[9]	AOUT[9]	AIN[11]	AOUT[12]	AIN[14]	AOUT[14]	AIN[16]	н
J	DATA[3]	AIN[8]	AOUT[8]	AIN[10]	AOUT[10]	AIN[13]	AOUT[13]	AIN[15]	AOUT[15]	J
	1	2	3	4	5	6	7	8	9	•

PIN DESCRIPTIONS_____

PIN NAME	I/O	Descriptions	
CLK	DI	System clock	
RSTN	DI	System reset. Active Low	
CSN	DI	Chip select. Active Low	
WRN	DI	Data write enable. Active Low	
DATA[3:0]	DIO	Data bus	
TEST_IN	DI	Tied to GND in Normal mode	
PAGE_UP	DI	Tied to GND in Normal mode	
VPP	PWR	Tied to GND in Normal mode	
AIN[31:0]	Al	Analog switch input	
AOUT[31:0]	AO	Analog switch output	
AVDD	PWR	Analog Power	
AVSS	GND	Analog Ground	
DVDD	PWR	Digital Power	
DVSS	GND	Digital Ground	

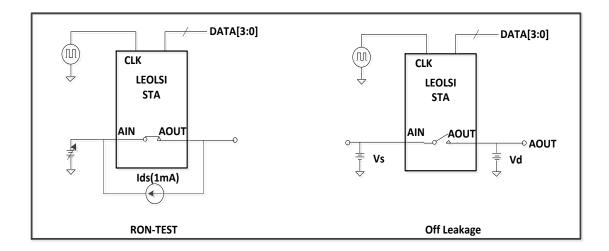
Al: analog input Dl: digital Input PWR: power AO: analog output DIO: digital Input / Output

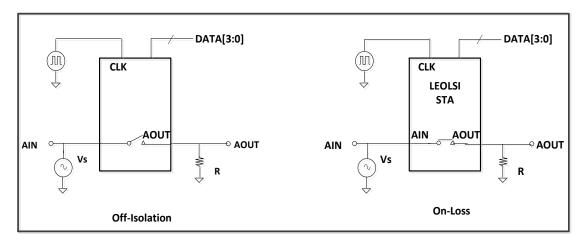
GND: ground



LEO LSI 8 DS_STA1.01_V1.4

TEST CIRCUITS





Off isolation=20log(V_{AOUT}/V_{AIN}), On Loss=20log(V_{AOUT}/V_{AIN})

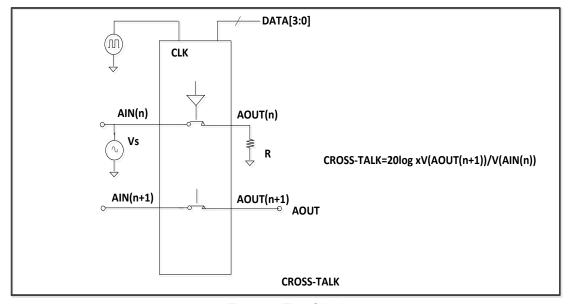
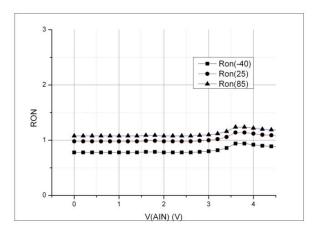


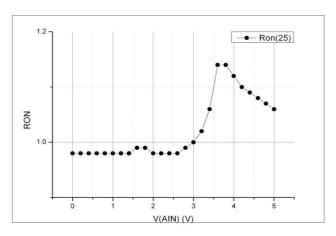
Figure 7. Test Circuits



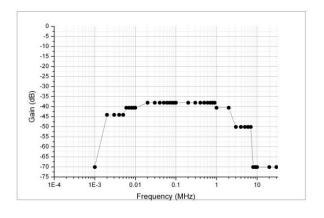
TEST RESULTS



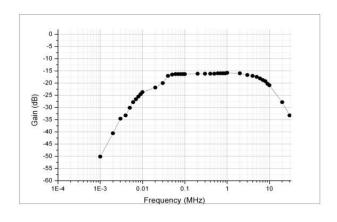
On-resistance vs. vain



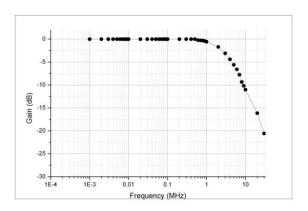
On-resistance(room temp) vs. vain



Cross talk vs. Frequency



Isolation vs. Frequency



On Loss vs. Frequency

Figure 8. Test Results



LEO LSI 10 DS_STA1.01_V1.4

DETAIL DESCRIPTIONS

Definitions

The STA1.0A IC consists of 8 cores which consist of 4 switches, hence it has 32 switches. The device provides one Chip-ID and it can be programmed in internal OTP memory. On the other hand, the eight Core-IDs are fixed in the device. The internal switch structure is shown in Figure 9. The Channel-ID is implicated in user defined commands interpreted in Digital Interface section.

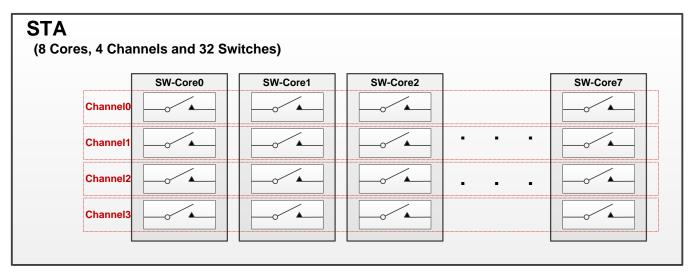


Figure 9. STA IC Internal Switch Structure and Definitions - Cores and Channels

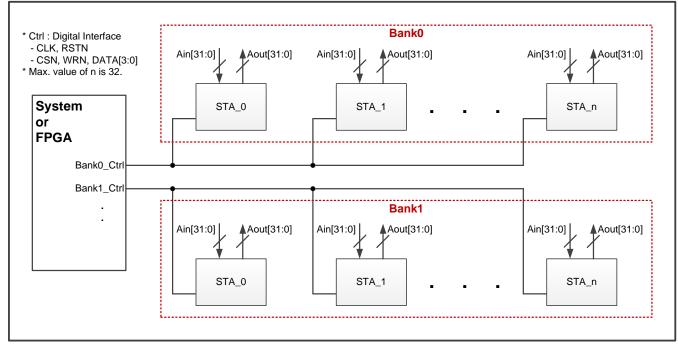


Figure 10. STA IC Application Structure and Definitions - Banks and Controls



In system application, two or more STA ICs can be controlled by the same digital interface - control and data signals such as CLK, RESETN, CSN, WRN and DATA[3:0] shown in Figure 10 and these STA IC network can be called as 'bank'. Because the Chip-ID is assigned in 5-bit address, the maximum number of STA IC in one bank is 32. Similarly, the Core-ID is assigned in 3-bit address hence 8 Cores are in one STA IC. The user can not apply the Chip-ID and the Core-ID to 1-clock command but to 2-clock command. Refer to Figure 12 and 13.

- Bank

The bank means STA network connected by the same digital interface - control and data signals such as CLK, RESETN, CSN, WRN and DATA[3:0]. Refer to the Figure 10.

- Reject

The individual switch control logic can be rejected from all commands. After entering reject state in which the switch is off, no command alters on/off state of rejected switch except the command 'INITIAL_ALL', 'CANCEL_REJECT' and external RSTN.

Digital Interface

- 1-Clock Command

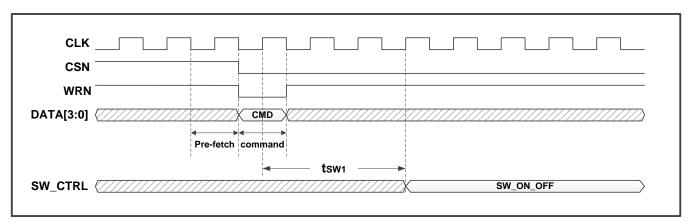


Figure 11. 1-Clock Command Control Timing Diagram

The 1-clock command is applied to all cores and all switches. Furthermore, this command is applied to all STA ICs in the same bank. The 'CMD' in Figure 11 means command which defines following modes:

Command	Value	Function
NORMAL	0x0	Returns to normal mode from Load mode (release all chip selection)
LOAD_ALL	0x1	Selects all chips to load(apply) the same commands
VIRTUAL	0x2	Programming mode for test
CLEAR_ALL	0x3	Makes all switches off
ENABLE_ALL	0x4	Makes all switches on
INITIAL_ALL	0x5	Initializes all switches releasing reject condition and making them on



LEO LSI 12 DS_STA1.01_V1.4

- 2-Clock Command

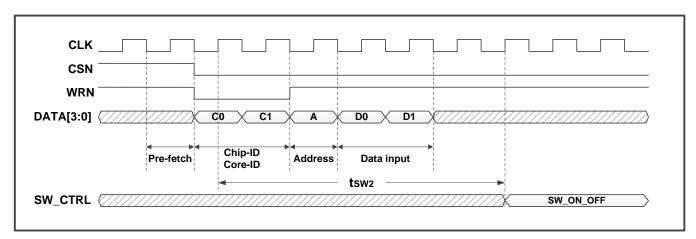


Figure 12. 2-Clock Command Control Timing Diagram

The '2-clock command' can control 8 Cores individually as well as simultaneously. Especially, the case of simultaneous 8 Core control can explain Channel-level switch control and it means that the users do not access Channel-ID directly.

In 2-clock command protocol, the signal DATA[3:0] can represent several items 'C0', 'C1', 'A', 'D0' and 'D1' shown in Figure 12 and these can be interpreted like as Figure 13.

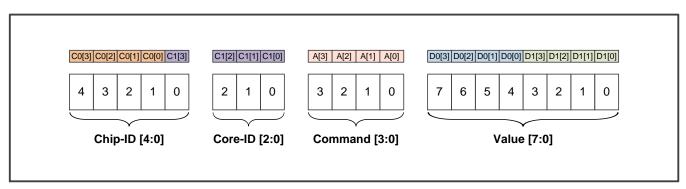


Figure 13. Interpretation of DATA[3:0] Signals in 2-Clock Command

The 'C0' and 'C1' are Chip-ID and Core-ID items and the address 'A' defines switch control Command. The Data 'D0' and 'D1' means the next state Value of 4 individual switches.

The 2-Clock command has three types of control.

- CHL(Chip-level): applied to all chips in the same bank (both Chip-ID and Core-ID are ignored)
- CRL(Core-level) : applied to all cores of selected chip (Chip-ID is referred but Core-ID is ignored)
- SWL(Switch-level): applied to selected switches of selected core (both Chip-ID and Core-ID are referred)

When the MSB of Command[3:0] is low, the Value[7:0] is applied to all Cores. Otherwise, the MSB of Command[3:0] is high, the Value[7:0] is applied to one Core selected by Core-ID[2:0].



The detail 2-Clock commands are given below.

Command	Value	Function	Remark
AND_CRL	0x0	Next switch status are produced by bitwise AND operation between current switch status and Data[7:0]. Applied to all cores of the selected chip.	CRL
OR_CRL	0x1	Next switch status are produced by bitwise OR operation between current switch status and Data[7:0]]. Applied to all cores of the selected chip.	CRL
DIRECT_CRL	0x2	Next switch status are produced by Data[7:0] directly. Applied to all cores of the selected chip.	CRL
DIRECT_CHL	0x3	Next switch status are produced by Data[7:0] directly. Applied to all cores of all chips in the same bank.	CHL
REJECT_CRL	0x4	Reject all switches of selected core by bitwise AND operation between current core reject status and Data[7:0].	CRL
-	0x5	Reserved	-
-	0x6	Reserved	-
-	0x7	Reserved	
AND_SWL	0x8	Next switch status are produced by bitwise AND operation between current switch status and Data[7:0]. Applied to the selected core.	SWL
OR_SWL	0x9	Next switch status are produced by bitwise OR operation between current switch status and Data[7:0]. Applied to the selected core.	SWL
DIRECT_SWL	0xa	Next switch status are produced by Data[7:0] directly. Applied to the selected core.	SWL
-	0xb	Reserved	-
REJECT_SWL	0xc	Reject selected switch by bitwise AND operation between current switch reject status and Data[7:0]	SWL
CANCEL_RJT	0xd	Cancel all switch-reject of selected core	-
-	0xe	Reserved	-
-	0xf	Reserved	-

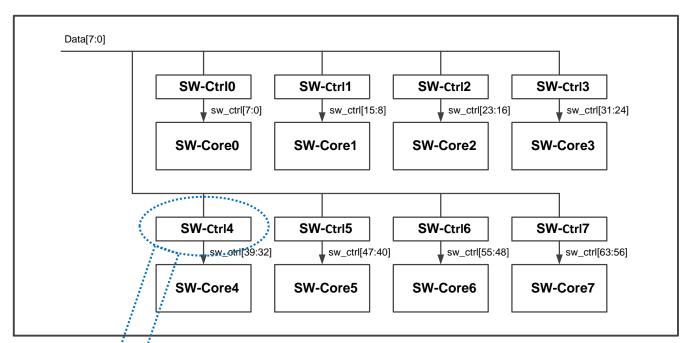


Figure 14. Switch Control Structure for 2-Clock Command

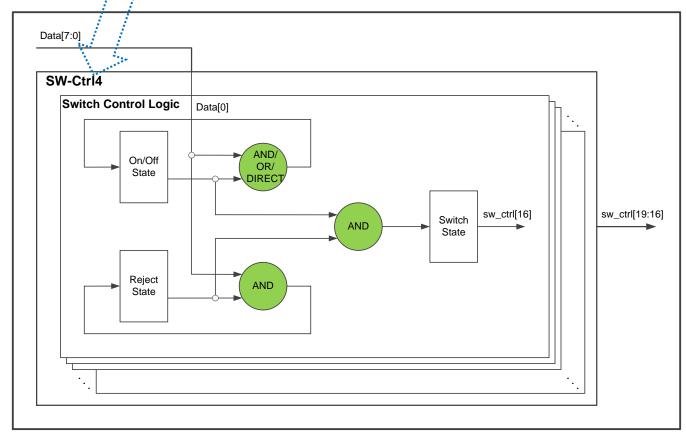


Figure 15. Basic Concept of 2-Clock Command Switch Control



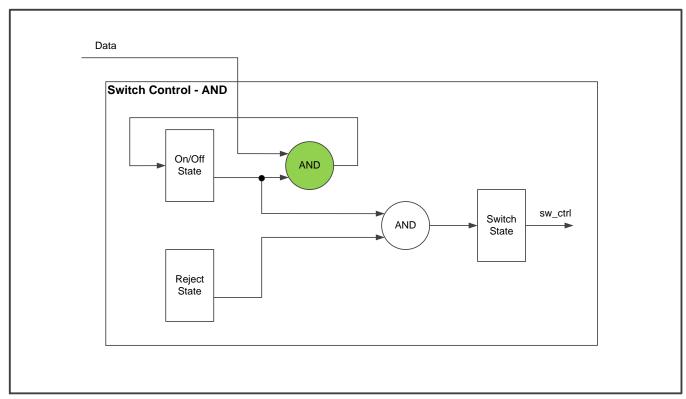


Figure 16. 2-Clock Command Switch Control - AND

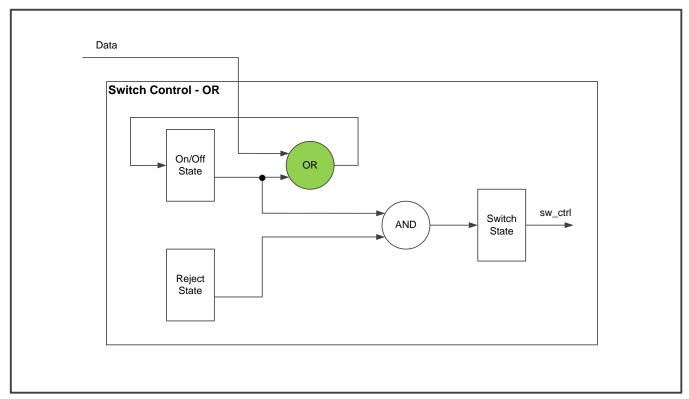


Figure 17. 2-Clock Command Switch Control - OR



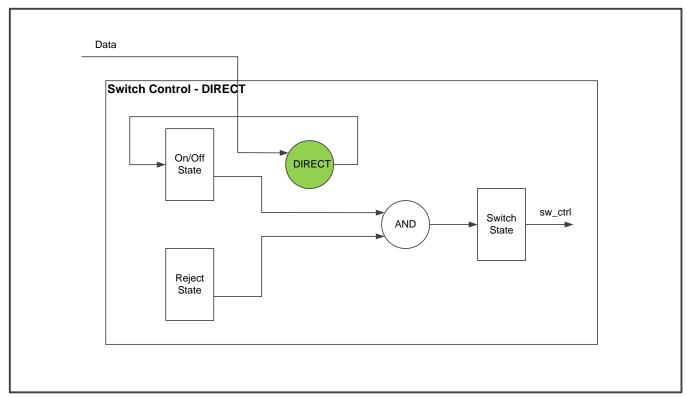


Figure 18. 2-Clock Command Switch Control - DIRECT

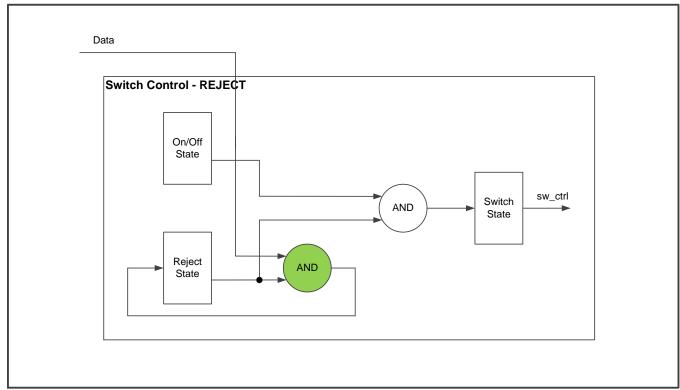


Figure 19. 2-Clock Command Switch Control - REJECT



APPLICATION EXAMPLE

The STA IC receives serial input data synchronized with a clock signal.

Most of all, to achieve maximum control speed in PCB, simulation using IBIS model should be carried out.

- 1. TEST_IN, PAGE_UP and VPP pins should be connected to ground through 20-k Ω (pull-down) resistor.
- 2. CSN pin should be connected to digital power through 20-k Ω (pull-up) resistor.
- 3. To guarantee the control speed, any resistor or capacitor should not be connected to CLK and DATA pins.
- 4. 10uF and 0.1uF decoupling capacitors should be connected to between AVDD and AVSS, and the same capacitors to between DVDD and DVSS.

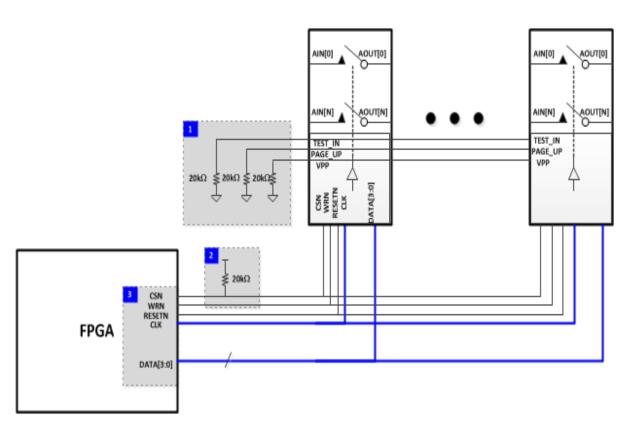
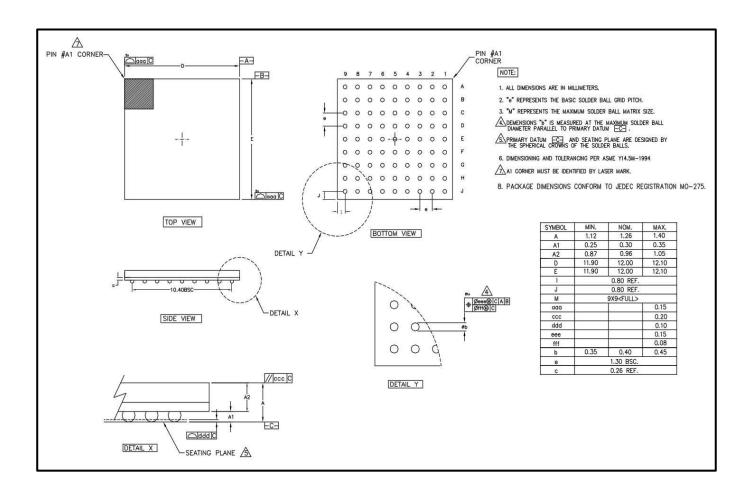


Figure 20. Application Example of PCB design

LEO LSI 18 DS_STA1.01_V1.4

PACKAGE INFORMATION



REVISION HISTORY

Revision	Date	Description
0.0	2012-06	Initial draft
1.0	2013-11	Revised format
1.1	2014-03	Gain loss graph in figure 8 was changed as TBD.
1.2	2014-06	AVSS power up sequence
1.3	2015-04	Decoupling capacitors for AVDD-AVSS and DVDD-DVSS
1.4	2016-03	Modified typical leakage current

DOCUMENT INFORMATION_

File name: STA1.01A Datasheet

Product code: STA1.01A
Product description: Analog Switch IC

Document revision: 1.4 Revision date: 2016-03



The world is driven by analog

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